

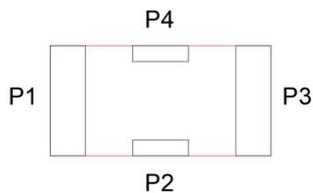
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

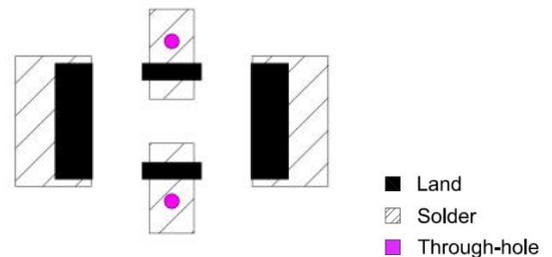
NO.	Parameter	SPC
1	Frequency range	DC-2750 MHz
2	Insertion Loss	1.2dB max. at +25°C; 3dB max. at +25°C @3230 MHz
3	Attenuation	20 dB min. @ 4000 MHz 30 dB min. @ 4100-6800 MHz 20 dB min. @ 4000-8400 MHz
4	VSWR (In BW)	1.5 max.; TYP1.2 max.
5	Port Impedance	50Ω
6	Power	10.0W max.
7	Operation Temperature Range	-55°C ~ +100°C

Construction



PIN	Connection
1	Input port
2	GND
3	Output port
4	GND

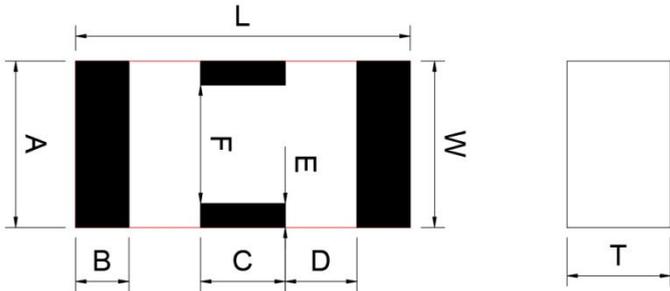
Mounting Considerations



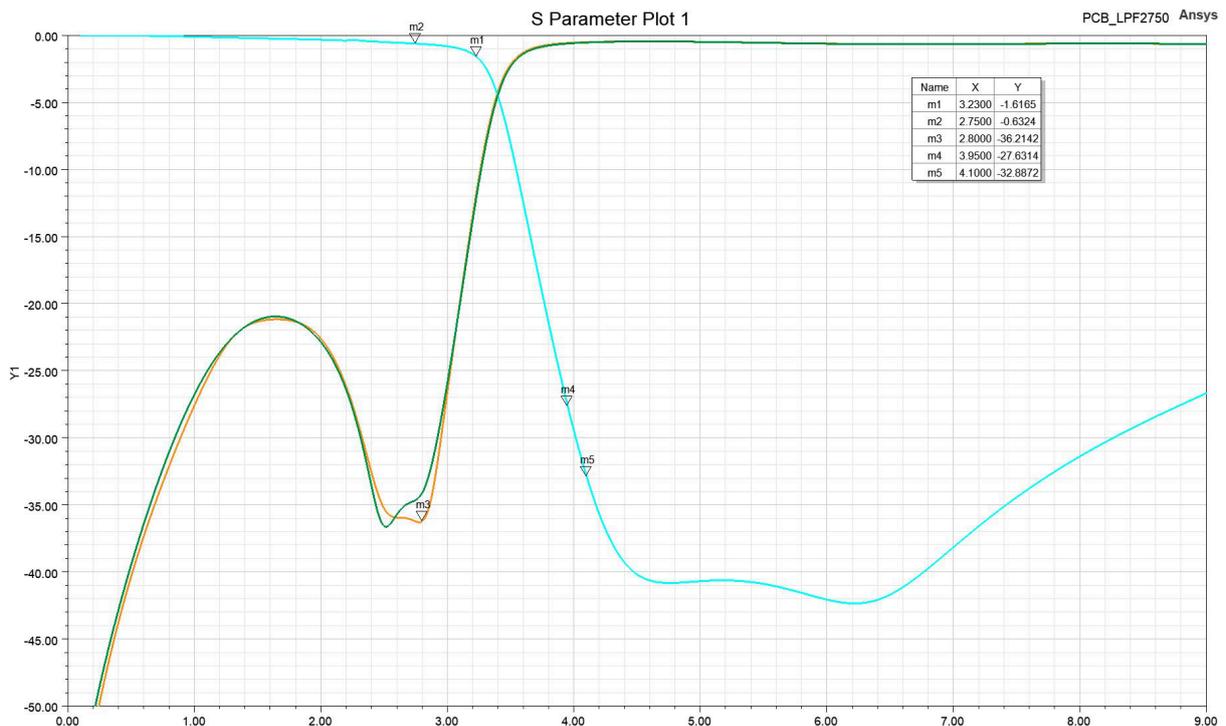
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

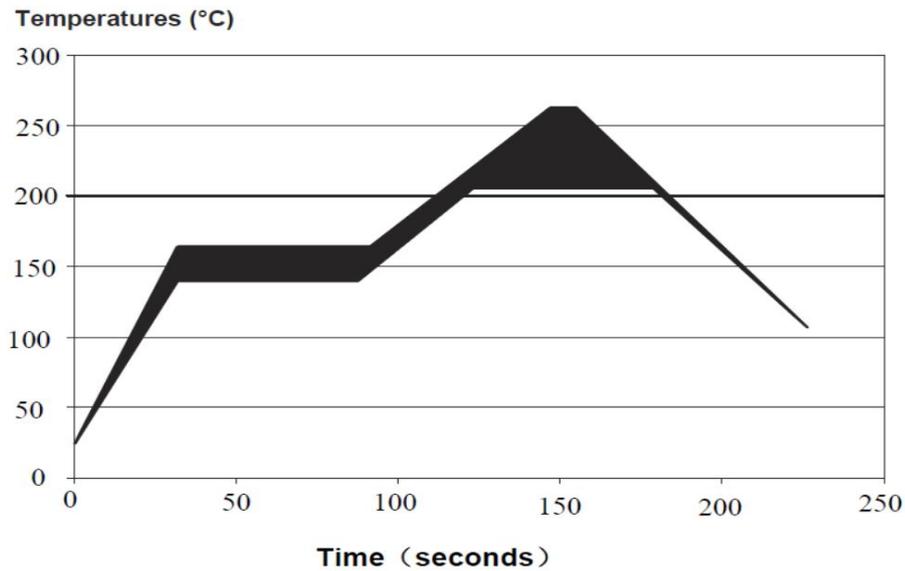
Dimensions

Figure	Symbol	Dimension (mm)
	L	3.2 ± 0.10
	W	1.6 ± 0.10
	T	1.0 ± 0.10
	A	1.6 ± 0.10
	B	0.51 ± 0.10
	C	0.81 ± 0.10
	D	0.685 ± 0.10
	E	0.23 ± 0.10
	F	1.14 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.